# ememory

### **Q4 2016 Investor Conference**

Feb. 15<sup>th</sup> , 2017

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### Outline

### Business Model

- Review of Operations for Q4 2016
- Future Outlook
- Q & A

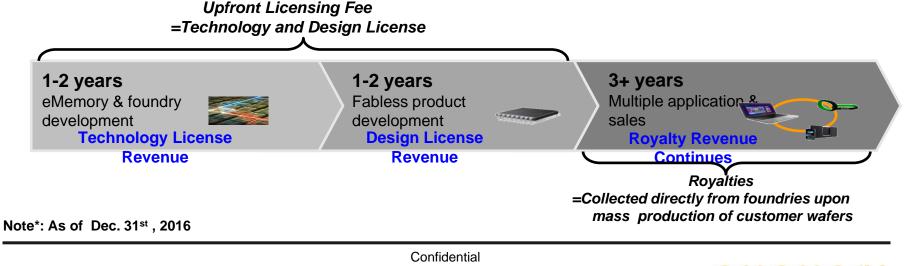


### **Business Model**

- Founded in 2000. First customer engaged in 2002. Achieved profitability in 2005 and IPO in 2011. The largest logic non-volatile memory IP company, 232 employees (162 R&D)\*.
- Since its IPO, the company initiated no new fund raising or bank debt, and has distributed in excess of 100% of earnings in cash dividends.
- Growth Indices: 1) No. of on-going technology platforms

2) No. of design licenses

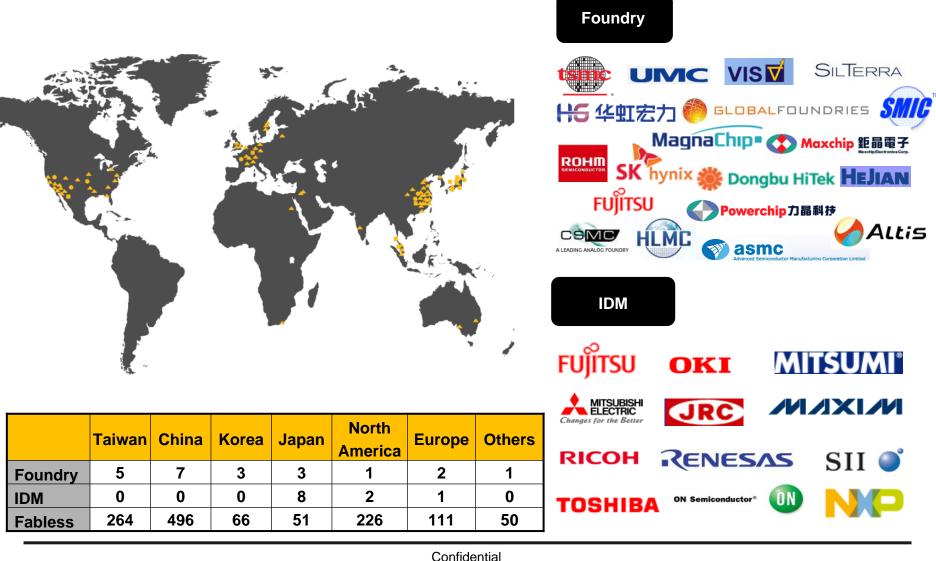
3) Royalty



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### **Worldwide Customers**

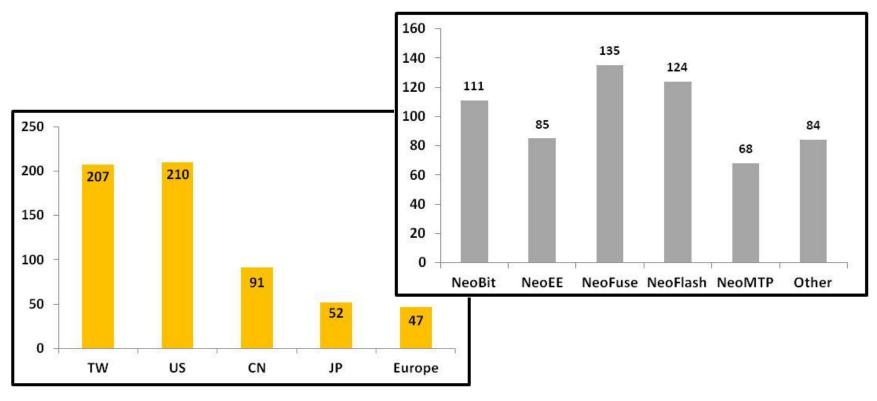


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### **Patent Portfolio**

	Q3 16	Q4 16	Diff.
Pending	204	218	+ 14
Issued	371	389	+ 18
Total	575	607	+ 32



Note\*: As of Dec. 31<sup>st</sup>, 2016

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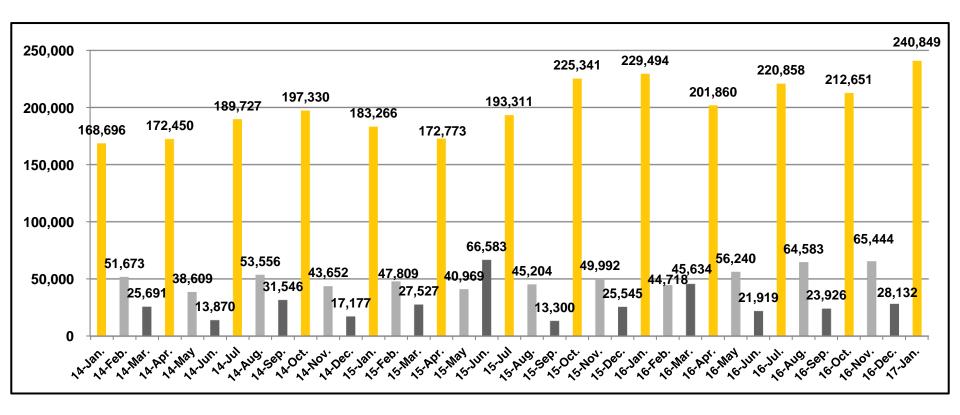


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### **Quarterly Revenue Pattern**

 The quarterly royalty from most of foundries are collected at first month of each quarter and from some other foundries are collected at second month, and none at third month.

Unit : NTD Thousands



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### **Q4 Revenue Breakdown**

#### **Unit: NTD thousands**

	Q4 2016	Q3 2016	QoQ	Q4 2015	YoY	2016	2015	YoY
Licensing	79,684	86,712	-8.10%	69,307	1 <b>4.97%</b>	330,087	267,512	23.39%
Royalty	226,543	222,655	1.75%	231,571	<b>-2.17%</b>	885,372	824,108	7.43%
Total	306,227	309,367	-1.01%	300,878	1.78%	1,215,459	1,091,620	11.34%

#### **Unit: Number of contracts**

		Q4 2016	Q3 2016	2016	2015
Technology Licenses		10	6	43	28
Design	NRE	12	18	56	57
Liconsos	Usage	73	81	311	349



### **Financial Income Statement**

(Unit: NTD thousands)	Q4 2016	Q4 2015	% change	2016	2015	% change
Revenue	306,227 *	300,878	1.8%	1,215,459 *	1,091,620	11.3%
Gross Margin	100% *	100%	-	100% *	100%	-
Operating Expenses	171,681 *	156,216	9.9%	685,650 *	570,403	20.2%
Operating Margin	43.9% *	48.1%	-4.2ppts	43.6% *	47.7%	-4.1ppts
Net Income	132,361 *	128,090	3.3%	534,917 *	479,111	11.6%
Net Margin	43.2% *	42.6%	+0.6ppts	44.0% *	43.9%	+0.1ppts
EPS (Unit: NTD)	1.75 *	1.69	3.6%	7.06 *	6.32	11.7%
ROE	28.3% *	28.4%	-0.1ppts	28.6% *	26.6%	+2.0ppts

\* Unaudited

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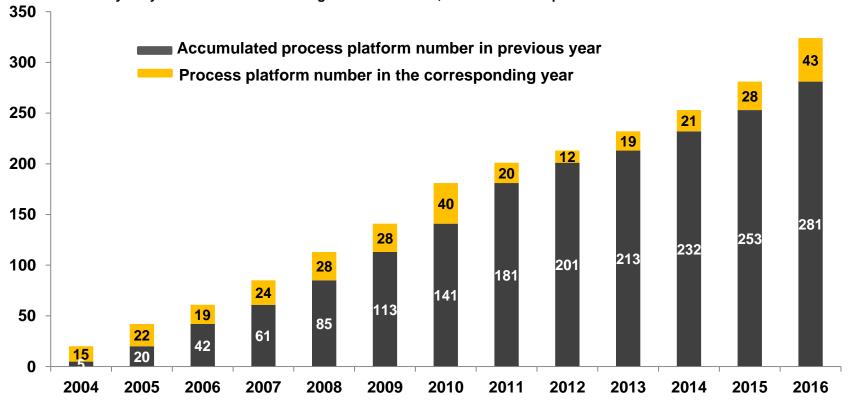


# **Technology License**

#### **Unit: Number of contract**

Year	2013	2014	2015	2016
License number	19	21	28	43

Note: The terms (including number of process platforms and licensing fees) for each technology license are set contractually. Payments are made according to set milestones, and there are no particular seasonal factors involved.



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### **Current Technology Development Platforms**

- Total (As of Dec.) : 104
- 19 for NeoBit, 43 for NeoFuse, 22 for NeoEE, and 20 for NeoMTP.

	7/10nm	14/16nm	28nm	40nm	55/65nm	80/90nm	0.11~ 0.13um	0.15~ 0.18um	>0.25 um
NeoBit	-	-	-	-	-	-	6	13	
NeoFuse	2	3	8	6	10	5	6	3	-
NeoFlash	-	-	-	-	-	-	-	-	-
NeoEE	-	-	-	-	-	-	5	17	-
NeoMTP	-	-	-	-	1	2	5	12	-

### **Current Technology Development Platforms**

12" Fabs	Production	Development	NVM Type	Process Type
7/10nm	0	2	ОТР	FF
14/16nm	1	3	ОТР	FF+
28nm	6	8	ОТР	LP/HPM, HLP/HPM, LPS
40nm	4	6	OTP, MTP	HV-DDI, LP
55/65nm	14	11	OTP, MTP, Flash	LP, HV-DDI, HV-OLED, DRAM, CIS
80/90nm	6	7	OTP, MTP	HV-DDI, HV-OLED, LP
0.13/0.11um	8	2	OTP, Flash	HV-DDI, BCD, Generic
0.18um	1	0	ОТР	BCD

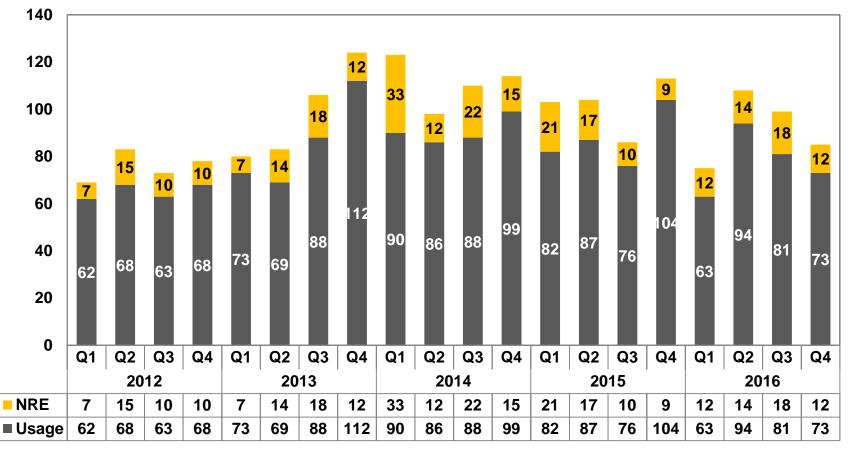
8" Fabs	Development	NVM Type	Process Type
0.13/0.11um	20	OTP, MTP, Flash	HV-DDI, BCD, LP, RF, CIS, LL
0.18/0.16/0.152um	45	OTP, MTP	Generic, LP, LL, MR, HV, Green, BCD
0.25um	0	OTP, MTP	BCD
0.35um	0	ОТР	UHV

Note\*: As of Dec. 31<sup>st</sup>, 2016



# Quarterly Design Licensing (New Tape Out)

- Total 367 NTO as of 2016( 406@2015,445@2014, 393@2013, 303@2012)

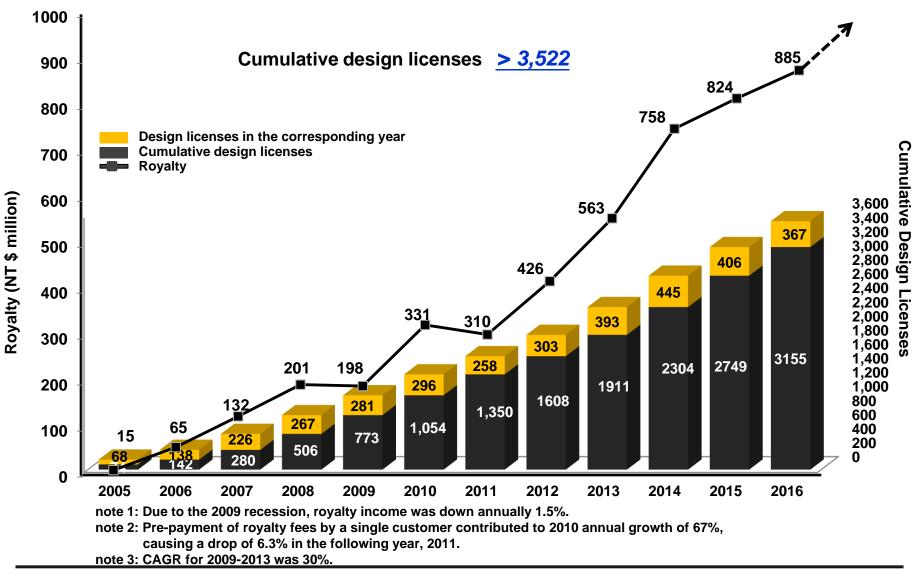


Note\*: As the applications of MCU at several foundries have gradually entered mass production, and the business model of the main foundry partner which provides green process has shifted to — eMemroy licenses IP cell to the foundry for it to provide direct design service to customers as the result, the new tape out number of MCU has been affected, but the royalty coming from IP cell usage continues to roll in. In summary, even the new tape out number of MCU is lower than before; the corresponding wafer output and royalty continue to grow.

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### **Cumulative Licenses Drive Future Royalties**

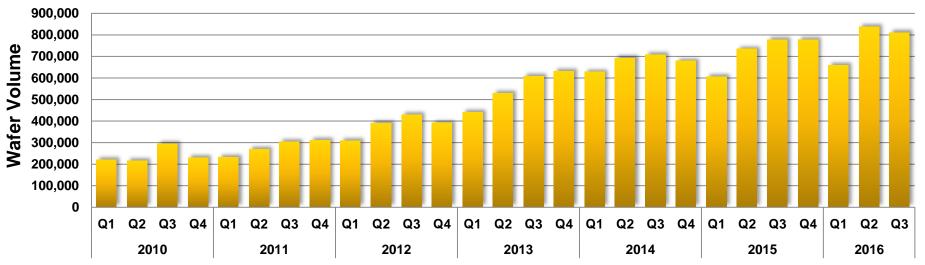


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### **Wafer Production Volume**



embedded eMemory IP in T Company (\$revenue); \* % of Process node in T company total revenue in Q4 2016

	Process node	*% of T	Q4 16	Q3 16	2016	2015
8"	0.25/0.35	2%	26.80%	26.44%	28.15%	33.49%
	0.15/0.18	10%	10.93%	13.07%	12.43%	8.73%
	0.11/0.13	2%	58.06%	40.96%	42.61%	29%
12"	90nm	5%	14.8%	3.83%	12.50%	19.85%
	65nm	11%	3.9%	3.85%	3.59%	0.55%
	40/45nm	12%	0	0	0.00%	0%
	28nm	24%	0.70%	0.61%	0.55%	0.05%
	16/20nm	33%	0%	0	0.00%	0%
8"		15%	18.60%	20.1%	18.86%	16.64%
12"		85%	1.56%	0.87%	1.44%	1.87%
Total		100%	4.12%	3.95%	4.27%	4.76%

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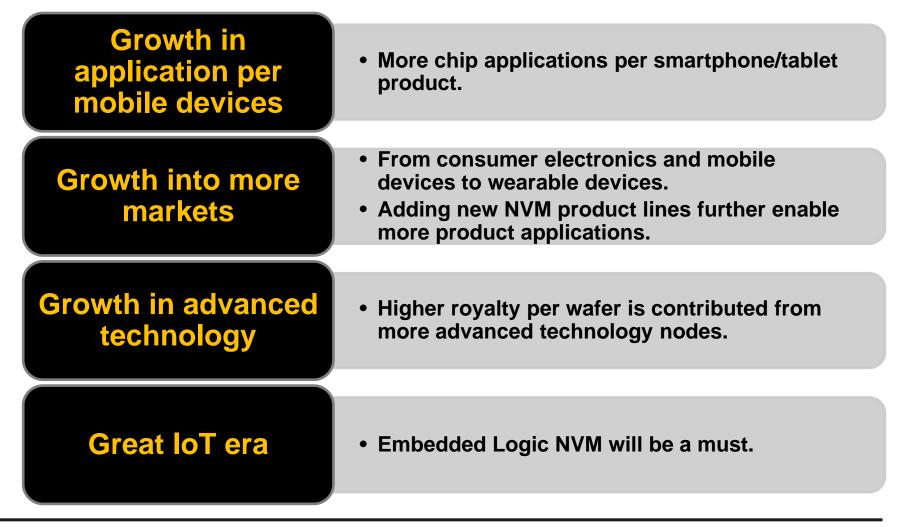
# **Outlook for 2017**

- In license revenues :
  - Strong demand for building advanced process and MTP platform in worldwide foundry partners will increase technology license and design license revenues.
- In royalty revenues :
  - > 8" wafer royalty will grow further due to multiple fingerprint customers are ramping up production and more customers will start volume production later this year.
  - > PMIC related royalty will increase due to new chips in fast charger
    ` wireless charger, and our largest US customer ramping up their new generation of PMIC in second half of 2017.
  - > Automotive platforms have been successfully built and customers already start small volume production

# **Outlook for 2017**

- > For 12" wafer royalty, the volume production of TDDI, OLED, STB/ DTV, CIS and security have continuously increased.
- > We had first 16nm tape-out in 2016. The 10nm IP have been successfully verified and 7nm test chip is expected to tape out in Feb. All these will increase our penetration rate in 12" fab.

# **Key Growth Drivers**



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## **Q & A**



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